

ABSTRACT OF THE DISCLOSURE

A manufacturing method of conductive paste comprising arranging process(S20 to S23) of ceramics particles, arranging process(S10 to S14) of wetted metal particles, forming process(S30) of slurry wherein metal particles and ceramics particles are mixed and dispersion treatment process(S32) by applying collision force to the slurry. The arranging process of wetted metal particles comprises, a process(S12) of adding solvent, compatible with organic component in conductive paste and incompatible with water, to undried water washed metal particles, a process(S18) of adding surfactant, a process(S14) of separating water from the metal particles and a process(S15) of adding acetone or the other second solvent.

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